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ABSTRACT OF THE DISCLOSURE

A chip-type semiconductor light-emitting device includes a semiconductor light-emitting chip connected to a pair of electrodes formed on a substrate. The semiconductor light-emitting chip is molded, together with respective parts of the electrodes, by resin. The electrode has a layered structure having a Cu layer, an Ni layer and an Au layer in the order of from the lowermost layer, to have a step formed inside the mold by changing the wall thickness of the Cu layer.